



YEA SHIN TECHNOLOGY CO., LTD

YSE2516QCE

Dual N-Channel Enhancement MOSFET

VDS= 20V, ID= 11A



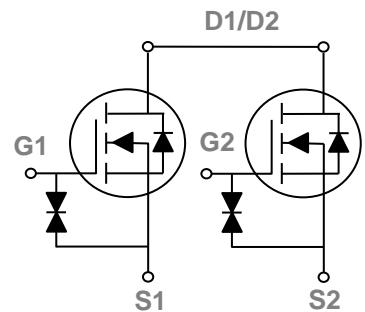
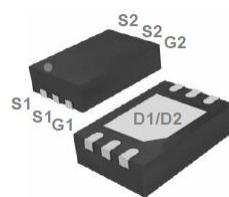
Features

- 20V, 11A, $R_{DS(ON)} = 8.2m\Omega$ @ $V_{GS} = 4.5V$
- Improved dv/dt capability
- Fast switching
- G-S ESD Protection Diode Embedded
- Green Device Available

Applications

- Handheld Instruments
- POL Applications
- Battery Protection Applications

DFN2x3 Dual Pin Configuration



Absolute Maximum Rating $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Drain Current – Continuous ($T_c=25^\circ C$)	11	A
	Drain Current – Continuous ($T_c=70^\circ C$)	8.8	A
I_{DM}	Drain Current – Pulsed ¹	70	A
P_D	Power Dissipation ($T_c=25^\circ C$)	1.56	W
	Power Dissipation – Derate above $25^\circ C$	0.0125	W/ $^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	80	$^\circ C / W$

DEVICE CHARACTERISTICS

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Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	20	---	---	V
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=18\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=25^\circ\text{C}$	---	---	1	μA
		$\text{V}_{\text{DS}}=16\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=70^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 12\text{V}, \text{V}_{\text{DS}}=0\text{V}$	---	---	± 10	μA

On Characteristics

$\text{R}_{\text{DS(ON)}}$	Static Drain-source On-Resistance	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=5.5\text{A}$	4.5	6	8.2	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4\text{V}, \text{I}_D=5.5\text{A}$	4.7	6.2	8.5	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=3.7\text{V}, \text{I}_D=5.5\text{A}$	5	6.5	9	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=3.1\text{V}, \text{I}_D=5.5\text{A}$	5.5	7	9.4	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=2.5\text{V}, \text{I}_D=5.5\text{A}$	6	8.2	11	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}, \text{I}_D=250\mu\text{A}$	0.5	0.72	1.5	V
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=5.5\text{A}$	---	20	---	S

Dynamic and Switching Characteristics

Q_g	Total Gate Charge ^{2,3}	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=11\text{A}$	---	15	30	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	2.8	5.6	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	4.4	8.8	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time ^{2,3}	$\text{V}_{\text{DD}}=15\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{R}_G=6\ \Omega, \text{I}_D=5.5\text{A}$	---	28	56	ns
T_r	Rise Time ^{2,3}		---	64	128	
$\text{T}_{\text{d(off)}}$	Turn-On Delay Time ^{2,3}		---	60	120	
T_f	Fall Time ^{2,3}		---	55	110	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=10\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{f}=1\text{MHz}$	---	1350	2500	pF
C_{oss}	Output Capacitance		---	185	350	
C_{rss}	Reverse Transfer Capacitance		---	160	300	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	11	A
V_{SD}	Diode Forward Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=1\text{A}, \text{T}_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

DEVICE CHARACTERISTICS

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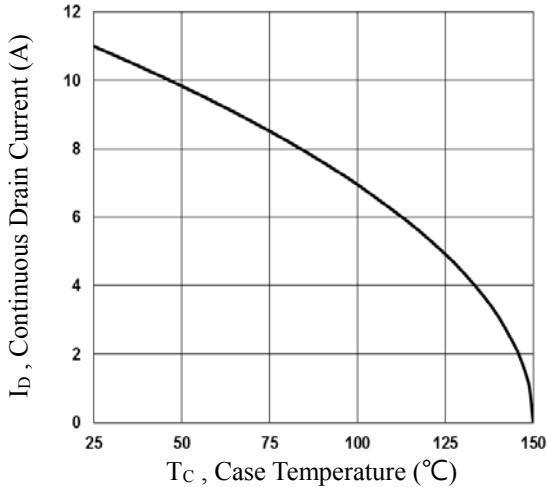


Fig.1 Continuous Drain Current vs. T_C

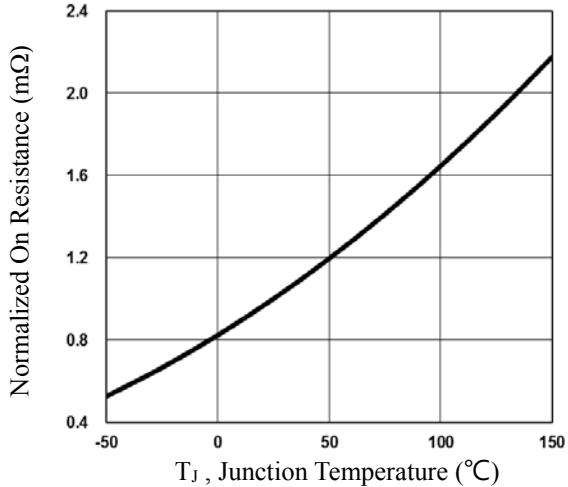


Fig.2 Normalized RDS(on) vs. T_J

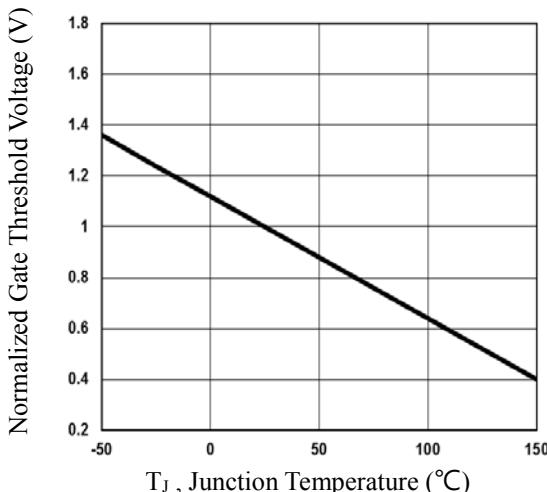


Fig.3 Normalized V_{th} vs. T_J

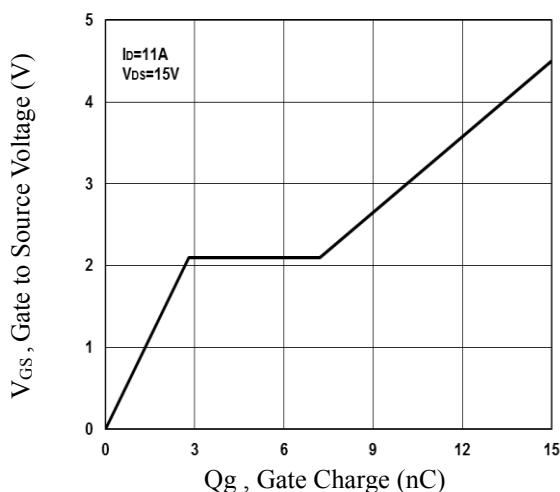


Fig.4 Gate Charge Waveform

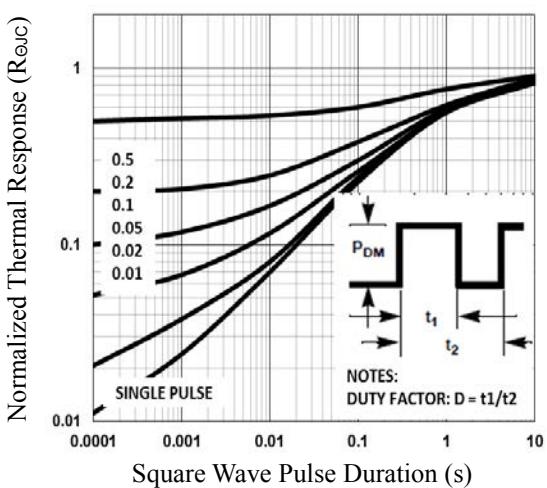


Fig.5 Normalized Transient Response

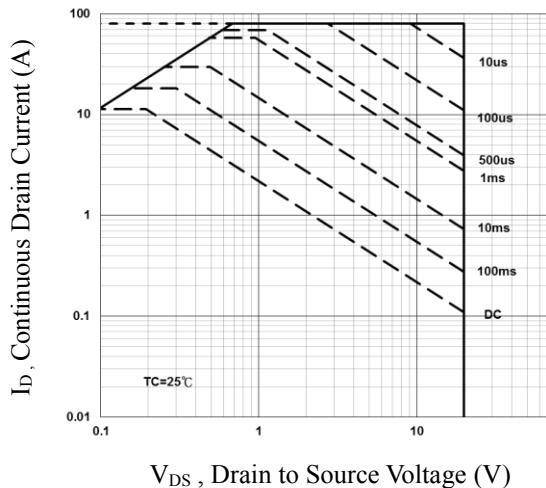


Fig.6 Maximum Safe Operation Area

DEVICE CHARACTERISTICS

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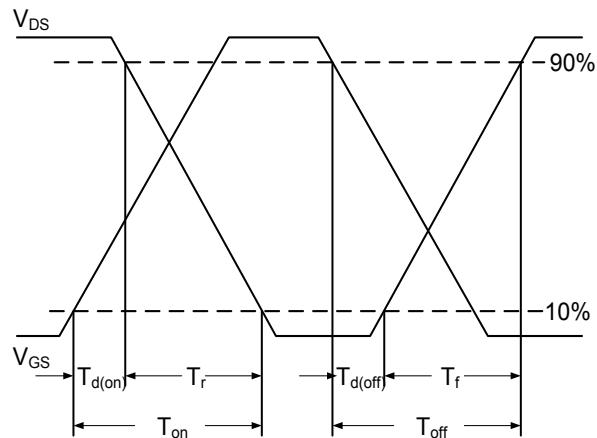


Fig.7 Switching Time Waveform

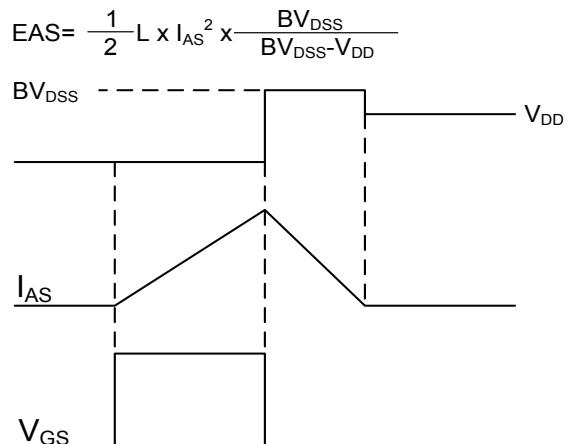
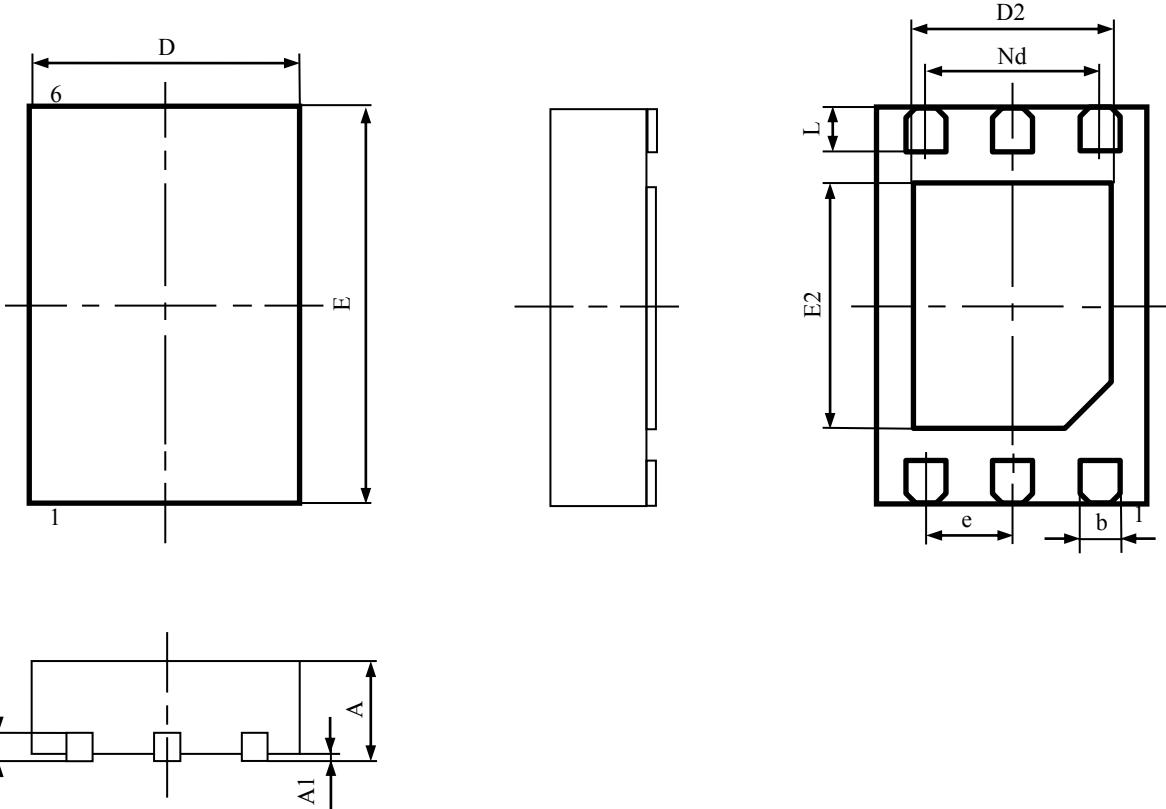


Fig.8 EAS Waveform

PACKAGE OUTLINE & DIMENSIONS

YSE2516QCE

DFN2X3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.800	0.700	0.031	0.028
A1	0.050	0.02typ.	0.002	0.001typ.
b	0.350	0.200	0.014	0.008
c	0.250	0.180	0.010	0.007
D	2.100	1.900	0.083	0.075
D2	1.600	1.400	0.063	0.055
e	0.5BSC		0.02BSC	
Nd	1.0BSC		0.04BSC	
E	3.100	2.900	0.122	0.114
E2	1.750	1.650	0.069	0.065
L	0.400	0.300	0.016	0.012